

WHAT IS CLAIMED IS:

1. A wiring board comprising a wiring layer formed on a surface of an electrically insulating substrate by transferring a wiring layer of a wiring transfer sheet, and at least an exposed area of the surface of the electrically insulating substrate is a first rough surface.

2. The wiring board according to claim 1, wherein the wiring transfer sheet includes a carrier base and the wiring layer formed on a surface of the carrier base, and at least an exposed area of the surface of the carrier base having the wiring layer formed thereon is a second rough surface; and

the first rough surface of the exposed area of the surface of the electrically insulating substrate is complementary to the second rough surface of the exposed area of the surface of the carrier base.

3. The wiring board according to claim 1, wherein at least the exposed area of the surface of the electrically insulating substrate has a plurality of convexities.

4. The wiring board according to claim 1, wherein the wiring transfer sheet includes a carrier base and a wiring layer formed on a surface of the carrier base, and at least an exposed

area of the surface of the carrier base having the wiring layer formed thereon has a plurality of concavities; and

the first rough surface of the exposed area of the surface of the electrically insulating substrate has convexities complementary to the concavities of the carrier base.

5. The wiring board according to claim 4, wherein the convexities occupy 50 to 98 % of the exposed area of the surface of the electrically insulating substrate.

6. The wiring board according to claim 4, wherein at least a portion of the convexities each have a diameter of between 0.5 and 5 μm at basis.

7. The wiring board according to claim 4, wherein the convexities each have a height of between 0.5 and 5 μm .

8. The wiring board according to claim 4, wherein at least a portion of the convexities each have a shape such that sections perpendicular to the height direction of the convexity are not uniform, and maximum-sized section having a maximum area is located at an intermediate position between a basis of the convexity and a top of the convexity.

9. The wiring board according to claim 8, wherein at

least a portion of the convexities each have a diameter of between 0.5 and 5 μm at the basis, and each have a diameter between 1 and 10 μm at the maximum-sized section.

10. The wiring board according to claim 1, wherein the wiring board is a multilayer wiring board including at least two electrically insulating substrates.

11. The wiring board according to claim 1, further comprising a component connected with the wiring layer and embedded in the electrically insulating substrate.

12. The wiring board according to claim 11, wherein the component extends within at least two adjacent electrically insulating substrates.

13. The wiring board according to claim 1, wherein the electrically insulating substrate has through holes formed in a thickness direction of the substrate, the through holes being filled with a conductive paste for electrically connecting wiring layers formed on both surfaces of the electrically insulating substrate.

14. The wiring board according to claim 11, wherein the component extends within at least two adjacent electrically

insulating substrates, and each of the electrically insulating substrates has through holes formed in a thickness direction of the substrate, the through holes being filled with a conductive paste for electrically connecting wiring layers arranged on both surfaces of the electrically insulating substrate.